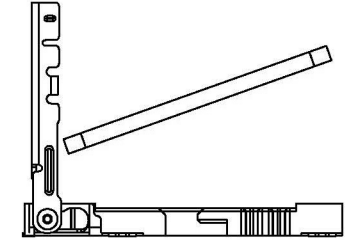
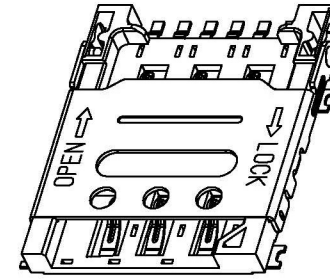
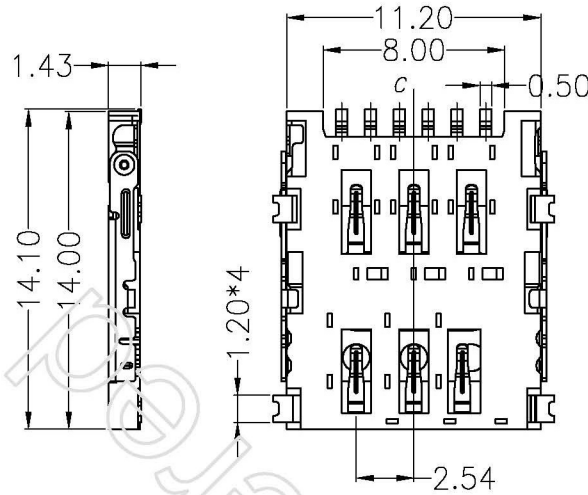
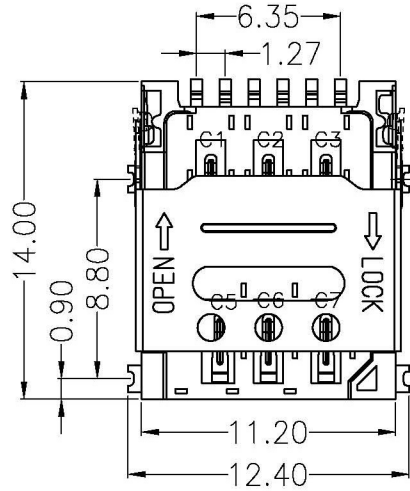
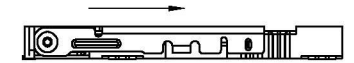


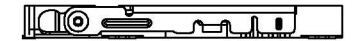
\* All Raw Material, Manufacturing, Plating process comply with ROHS



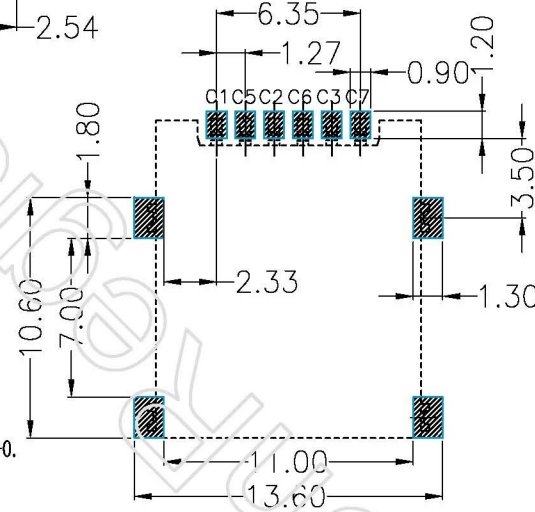
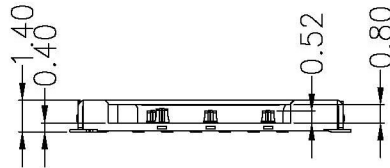
STEP 1 INSERT NANO SIM CARD



STEP 2 PUSH THE SHELL



STEP 3 FINISH



FCB 焊盘区

RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0,  
Contact: C5210  
SHELL: SUS

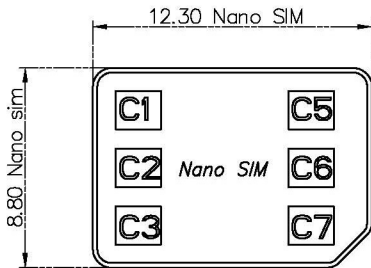
PLATING:

Contact: Plated 50u'' Ni Overall Contact ALL Au 1U,  
Shell: ALL NI 30U/MIN

Electrical:

Current Rating :0.5mA AC/DC max.  
Voltage Rating :125V AC/DC  
Ambient Temperature Range :-40° C~+85° C  
Storage Temperature Range :-40° C~+85° C  
Ambient Humidity Range :95% R.H. Max.  
Contact Resistance:80m Ωmax.  
Insulation Resistance:100M Ωmin./100V DC  
Mating Cycles:10,000 Insertions  
Reflow peak temp. : 260° C ±5° C, 3~5 S

PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



<p>连欣科技 Lian Xin Technology</p>	<h2>深圳市连欣科技有限公司</h2>				
	DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : NANO-SIM 掀盖式1.40H 6PIN	DRAWING: <b>COCO</b>	DATE: 2017/11/20	
	DIMENSION TOLERANCE X.X: ± 0.15 X.XX: ± 0.10 X.XXX: ± 0.05 ANGULAR: ± 1°	PRODUCT NO. : XDSM-0639-0250	CHECK: <b>JANY</b>	DATE: 2017/11/20	
		DRAWING NO. : 0250 AAAG06A	APPROVED:	DATE: 2017/11/20	
		SCALE: 1:1	DWG TD: C D	REV.: A	PAGE: 1 of 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				